Customer:	**Maxim_Jason Altsuler**	**Date:**	**01/21/16**
Part # :	**MAX2175_EVKIT_C**	**Job # :**	
Mat. Typ:	**FR4 High temp**	**Impedance Stack-Up**	**Layers: 6**

Network PCB
1914 Otoole Way
San Jose CA 95131
408-943-8760

Layer Number	Layer Type	Copper Weight (oz)	Copper Thickness (in.)	Dielectric Thickness (in.)			Dielectric Material	Impedance Single Ended +/-10%	Line Width		Impedance Differential +/- 10%	Line Width trace/space		Impedance Differential +/- 10%	Line Width trace/space		
				FOIL													
1	Top		0.0014					**50ohm**	**20.5mil**		**50ohm**	**47/8mil**		**100ohm**	**15/14mil**		
				0.0125			B-STAGE										
2	Gnd		0.0014														
				0.008			CORE										
3	Sig		0.0014														
				0.01			B-STAGE										
4	Sig		0.0014														
				0.008			CORE										
5	Gnd		0.0014														
				0.0125			B-STAGE										
6	Bot		0.0014											**100ohm**	**15/14mil**		
				FOIL													

Thickness at Lamination (in): 0.0594 +/- 0.003
Thickness with Plating (Cu to Cu) (in): 0.062 +/- 0.006